



Material Content Data Sheet



Sales Product Name				IPD30N03S4L-14		Issued		19. January 2018	
MA#				MA001913474					
Package				PG-TO252-3-11		Weight*		368.91 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.562	0.15	0.15	1523	1523	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175		
	non noble metal	iron	7439-89-6	0.215	0.06		584		
	non noble metal	copper	7440-50-8	215.017	58.29	58.37	582844	583603	
	non noble metal	aluminium	7429-90-5	0.775	0.21	0.21	2101	2101	
wire	non noble metal	aluminium	7429-90-5	0.775	0.21	0.21	2101	2101	
encapsulation	organic material	carbon black	1333-86-4	1.284	0.35		3480		
	plastics	epoxy resin	-	22.466	6.09		60897		
	inorganic material	silicondioxide	60676-86-0	104.626	28.36	34.80	283607	347984	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10138	10138	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	246	247	
solder	non noble metal	tin	7440-31-5	0.017	0.00		47		
	noble metal	silver	7440-22-4	0.022	0.01		59		
	non noble metal	lead	7439-92-1	0.829	0.22	0.23	2246	2352	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	iron	7439-89-6	0.019	0.01		52		
	non noble metal	copper	7440-50-8	19.177	5.20	5.21	51984	52052	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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